





Delivering Value through Innovation and Dedication

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## ThunderClad 5Q\_TU-953Q

**Core: TU-953Q** 

Prepreg: TU-953P Q

**TU-953Q** is an advanced material designed for high speed computing, telecommunications, radio frequency super low loss filed applications. **TU-953Q** electrical performance is competitive with PTFE-based, hydrocarbon-based very low loss materials, but capable for high layer count circuit board design with excellent thermal reliability.

**TU-953Q** laminates also exhibit excellent moisture resistance, improved CTE, superior chemical resistance, thermal stability, CAF resistance, and also compatible with modified FR-4 processes.

#### **Applications**

- Al Servers, Networking
- · Backplane, High performance computing
- Line cards, Storage
- Servers, Telecom, Base station
- Office Routers

#### Performance and Processing Advantages

- Excellent electrical and thermal properties
- Dielectric constant is 2.99 @ 10GHz
- Dissipation factor is 0.00074 @ 10GHz
- Stable and flat Dk/Df performance over frequency and temperature variance.
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Improved z-axis thermal expansion
- Superior dimensional stability, thickness uniformity and flatness
- Anti-CAF capability
- · Excellent through-hole and soldering reliability
- Halogen Free

#### **Industry Approvals**

- IPC-4101E Specification Number: /134
- UL File Number: E189572
- ANSI Grade: No-ANSI
- Flammability Rating: 94V-0
- Maximum Operating Temperature: 170°C

### Standard Availability

- Thickness: 0.002" [0.05mm] to 0.028" [0.71mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 2 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 1035, 1078

The newly developed products are slightly modified and updated after more data has been collected.



# Extreme Low Loss and High Thermal Reliability Laminate and Prepreg







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	Typical Values	Conditioning
Thermal		
Tg (DMA) Td (TGA)	200 ℃ 430 ℃	E-2/105
CTE x/y axis CTE z-axis α1 CTE z-axis α2 CTE z-axis	5/6 ppm/°C 40 ppm/°C 150 ppm/°C 1.5%	E-2/105
Thermal Stress, Solder Float, 288°C	> 120 sec	A
T-260 T-288 T-300	> 60 min > 60 min > 60 min	E-2/105
Flammability	94V-0	E-24/125
Electrical		
Permittivity (RC70%) 10 GHz (SCR method)	2.99	E-2/105
Loss Tangent (RC70%) 10 GHz (SCR method)	0.00074	E-2/105
Volume Resistivity	> 10¹0 MΩ∙cm	C-96/35/90
Surface Resistivity	$> 10^8~\text{M}\Omega$	C-96/35/90
Electric Strength	> 40 KV/mm	Α
Dielectric Breakdown Voltage	> 50 KV	A
Mechanical		
Young's Modulus Warp Direction Fill Direction	25 GPa 24 GPa	А
Flexural Strength Lengthwise Crosswise	> 60,000 psi > 50,000 psi	Α
Peel Strength, H oz HVLP4 Cu foil	2~3 lb/in	A
Moisture Absorption	0.03 %	E-1/105 + D-24/23

#### NOTE

- $1.\ Property\ values\ are\ for\ information\ purposes\ only\ and\ not\ intended\ for\ specification.$
- 2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
- 3. This product is based on a patent pending technology.



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